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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Lamson et al.

Docket No.: TI-31189

Serial No.: 09/989,263

Examiner: Maldonado, J.

Filed: 11/19/01

Art Unit: 2823

For: LOW CAPACITANCE COUPLING WIRE BONDED  
SEMICONDUCTOR DEVICE

INFORMATION DISCLOSURE STATEMENT

Assistant Commissioner for Patents  
Washington, DC 20231

Dear Sir:

<p><b>MAILING CERTIFICATE</b></p> <p>I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, DC 20231.</p> <p>Date <u>8-27-02</u></p> <p><u>Marianna Smith</u></p> <p>Marianna Smith</p>
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Please make the references listed on the enclosed PTO-1449 of record under 37 C.F.R. 1.56, 1.97, and 1.98 in the patent application identified above. They were cited in a corresponding European patent application. Copies of the listed references and European search report are enclosed.

Respectfully submitted,

*Michael K. Skrehot*

Michael K. Skrehot  
Attorney for Applicants  
Reg. No. 36,682

Texas Instruments Incorporated  
P. O. Box 655474, MS 3999  
Dallas, Texas 75265  
(972) 917-5653  
FAX: (972) 917-4418  
(972) 917-4417